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(54) **LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE COMPOSITION AND A METHOD INCLUDING THE SAME**

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(58) **Field of Classification Search**
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See application file for complete search history.

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(57) **ABSTRACT**

The invention features a hot melt adhesive composition that can be applied at temperatures as low as 107° C., while maintaining excellent bonding under stress and a very fast setting time.

16 Claims, No Drawings